IPC  ASSOCIATION CON ELECTRONICS INC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfc Information				
upplier In	nformation														
Company name*			Company un	Company unique ID			Unique ID Authority				Response Date*				
nsemi										2023-06-08					
Contact Name	e	Title - Contact			I	Phone - Contact*				Email - Contact*					
Product-Env-	-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorized Re	epresentative*	Title - Representative			I	Phone - Representative*			Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Re	Requester Item Number		Mfr Item Number Mfr Item Nar		ne		Effective Date	Version	N	Manufacturing Site	Wei	ght*	UOM	Unit Type	
		NCP571MN10TBG LDO		LDO	00		2023-06-08 MY1		20.0		mg	Each			
Ianufactu	ring Proccess Inform	ation						·					·		
Terminal Plating / Grid Array Material Terminal Ba			erminal Base	rminal Base Alloy J-STD-020 MSL Rating			Peak Process Body Temperature Max Time at Peak T				Temperature Number of Reflow Cycles				
Ma	atte Tin (Sn) - annealed	(	CU Alloy	1			260		C	30	seconds	3			
omments															
vel 1 - maxir	mum time at peak tempera	ture during sol	dering is 10-3	30 seconds											
or more info	ormation regarding materia	al composition	please refer t	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct omponents, the declaration shall encompass all such components. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.2	mg
Die Attach	0.45	mg	Supplier	Silver (Ag)	7440-22-4		0.3375	mg
			Supplier	Epoxy resins	129915-35-1		0.1125	mg
Lead Frame	6.97		Supplier	Silver (Ag)	7440-22-4		1.9446	mg
			Supplier	Iron (Fe)	7439-89-6		0.0767	mg
			Supplier	Copper (Cu)	7440-50-8		4.9487	mg
Mold Compound-Black	10.0			Epoxy resin	proprietary data		0.7	mg
			Supplier	Phenolic Resin	Proprietary Data		0.7	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.5	mg
			Supplier	Carbon Black (C)	1333-86-4		0.05	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		7.05	mg
Plating	0.71	mg	Supplier	Tin (Sn)	7440-31-5		0.71	mg
Wire Bond - Au	1.67	mg	Supplier	Gold (Au)	7440-57-5		1.67	mg